# Molex 736420000 PDF

# molex

深圳创唯电子有限公司 http://www.molex-connect.com





LANGUAGE

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#### Introduction

Bellcore has proposed generic requirements for separable electrical connectors used in telecommunications hardware (TR-NWT-001217, Issue 1, Nov. 1995). Many customers who choose to utilize the HDM (High Density Metric) product line, as manufactured by Molex, require that the product perform up to the standards as established by Bellcore. This report will summarize the performance of the Molex HDM product as submitted to an outside source and tested to the TR-NWT-001217. The specific testing procedures applied, equipment utilized, and raw data can be acquired from Molex upon request.

#### **Product Description**

The test boards utilized for the Bellcore test consisted of two 144 signal modules separated by a guidance module. The backplane pins were lubricated using Molex environmental barrieEB-1. The daughtercard assembly is available under Molex part number 73670-0083. When measuring mating and unmating forces, the values are for the full assembly (288 signal pins and guide module). Also, the variation in initial measurement values (between minimum and maimum) for the Low Level Circuit Resistance (LLCR) is due to the variation in bulk resistance between rows A and F.

The following sections give the group description of the tests completed and the results for each step completed during testing.

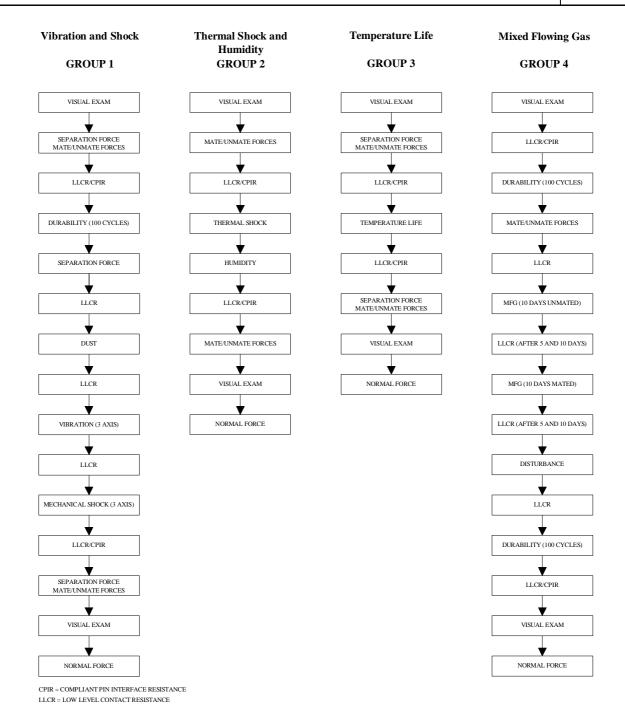
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## **Test Performance**

Group 1

		REVISE ON PC ONLY	TITLE	Ξ.					
	A	SEE SHEET 1	BELLCORE SUMMARY FOR HDM (HIGH DENSITY METRIC)						
	REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
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		ES-4000-3996 REV. A S	HEET 8	95/MAR/10 EC	U5-0926 DCBRD0	7.MWP			





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<b>Test Condition</b>	Requirement	Units	Minimum	Maximum	
Visual	Appearance		No Damage	;	
Compliant Resistance	Record	mΩ	0.65	1.28	
Separation Force	Record	oz.	0.6	1.3	
Mating Force	Record	lbs.	25.5	32.0	
Unmating Force	Record	lbs.	26.3	30.3	
LLCR	Record	m $\Omega$	11.3	38.7	
Durability	Appearance		No Damage	;	
Separation Force	Record	OZ.	0.8	1.2	
LLCR	10 Max (change from initial)	$m\Omega$	N/A	2.4	
Dust	Apply		Applied		
LLCR	10 Max (change from initial)	mΩ	N/A	2.8	
Vibration	Appearance		No Damage	;	
(3 - axis)	10 Max (detect)	nanosecond	issed		
LLCR	10 Max (change from initial)	mΩ	N/A	3.4	
Shock	Appearance		No Damage	;	
(3 - axis)	10 Max (detect)	nanosecond	Pa	issed	
LLCR	10 Max (change from initial)	mΩ	N/A	3.0	
Compliant Resistance	1 Max (change from initial)	mΩ	N/A	0.20	
Mating Force	Record	lbs.	28.9	31.2	
Unmating Force	Record	lbs.	27.8	29.4	
Separation Force	Record	OZ.	0.8	1.4	
Visual	Appearance		No Damage		
Normal Force	Record	grams	59	77	

# Group 2

<b>Test Condition</b>	Requirement	Units	Minimum	Maximum		
Visual	Appearance	No Damage				
Compliant Resistance	Record	mΩ	0.78	1.25		

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Mating Force	Record	lbs.	28.2	30.0		
Unmating Force	Record	lbs.	25.3	26.5		
LLCR	Record		11.7	32.1		
Thermal Shock	Appearance	No Damage				
Humidity	Appearance	No Damage				
LLCR	10 Max (change from initial)	mΩ	N/A	3.6		
Compliant Resistance	1 Max (change from initial)	mΩ	N/A	0.35		
Mating Force	Record	lbs.	31.1	36.9		
Unmating Force	Record	lbs.	26.4	35.5		
Visual	Appearance	No Damage				
Normal Force	Record	grams	55	70		

# Group 3

# Group 3 (cont.)

<b>Test Condition</b>	Requirement	Units	Minimum	Maximum		
Visual	Appearance	No Damage				
Normal Force	Record	grams	54.4	75		

<b>Test Condition</b>	Requirement	Units	Minimum	Maximum
Visual	Appearance		No Damage	
Compliant Resistance	Record	${ m m}\Omega$	0.82	1.3
Separation Force	Record	lbs.	0.6	1.3
Mating Force	Record	lbs.	28.2	30.1
Unmating Force	Record	lbs.	20.4	27.4
LLCR	Record	mΩ	11.6	31.7
Temperature Life	Appearance		No Damage	
LLCR	10 Max (change from initial)	mΩ	N/A	1.1
Compliant Resistance	1 Max (change from initial)	mΩ	N/A	0.28
Mating Force	Record	lbs.	17.4	21.6
Unmating Force	Record	lbs.	13.5	17.7
Separation Force	Record	OZ.	0.5	1.4

# Group 4

<b>Test Condition</b>	Requirement	Units	Minimum	Maximum
Visual	Appearance		No Damage	

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Compliant Resistance	Record	mΩ	0.72	1.28		
LLCR	Record	mΩ	11.5	31.7		
Durability	Appearance		No Damage			
Mating Force	Record	lbs.	29.4	32.8		
Unmating Force	Record	lbs.	23.6	31.8		
LLCR	10 Max (change from initial)	mΩ	N/A	0.3		
MFG, Unmated	Appearance		No Damage			
LLCR, 5 day	10 Max (change from initial)	mΩ	N/A	0.6		
LLCR, 10 day	10 Max (change from initial)	mΩ	N/A	2.2		
MFG, Mated	Appearance	No Damage				
LLCR, 5 day	10 Max (change from initial)	mΩ	N/A	1.5		
LLCR, 10 day	10 Max (change from initial)	mΩ	N/A	1.3		
Disturbance	Appearance		No Damage			
LLCR	10 Max (change from initial)	mΩ	N/A	1.8		
Durability	Appearance		No Damage			
LLCR	10 Max (change from initial)	mΩ	N/A	1.5		
Compliant Resistance	1 Max (change from initial)	mΩ	N/A	0.58		
Visual	Appearance		No Damage			
Normal Force	Record	grams	64.6	76.7		

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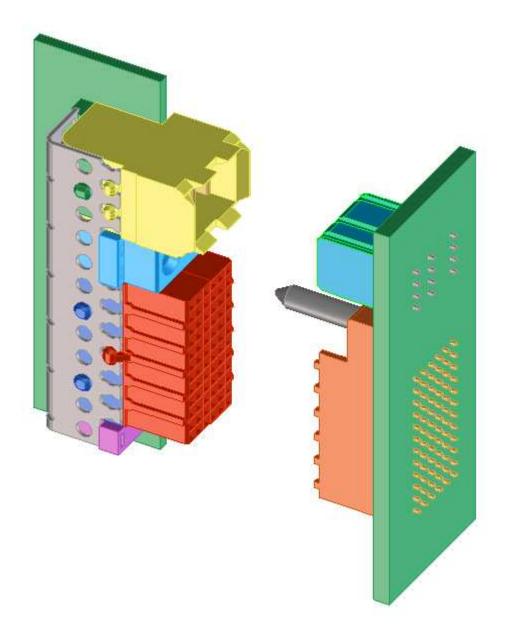
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# PRODUCT SPECIFICATION FOR HIGH DENSITY METRIC (HDM) BACKPLANE AND DAUGHTERCARD INTERCONNECT SYSTEM



REVISION:	ECR/ECN INFORMATION:	PRODUCT SPECIFICATION FOR HIGH		SHEET No.	
G	EC No: UCP2009-2455	DENS	SITY METRIC (HDN	<b>/</b> I)	<b>1</b> of <b>7</b>
G	DATE: 2009/06/22	INTER	CONNECT SYSTE	ΕM	1017
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPRO\	/ED BY:
PS-73670-9999		S. DANNELLEY	B. SMART	S. MII	LER
FUENAME POTOSTOO					



#### 1.0 SCOPE

This specification covers the performance requirements and test methods for the following products listed by series numbers:

\* 73642, 73643, 73644, 73650, 73942, HDM Backplane Signal Module 73943, 73944, 74992, 74349, 74301

\* 73656, 73659
 \* 73670
 HDM Backplane Power Module
 HDM Daughtercard Assembly

73998 HDM Vertical Daughtercard Power Module

The HDM backplane interconnect system consists of 2mm 6 row modular configurations with custom signal, power and guidance modules. These connectors are two-piece devices, which connect two printed circuit boards. The right angle receptacle connectors (daughtercard) and header pin connectors (backplane) are through hole devices with solder or eye-of-the-needle compliant pin terminals.

#### 2.0 PRODUCT DESCRIPTION

#### 2.1 PRODUCT NAMES

HDM (High Density Metric)

#### 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

Refer to the appropriate sales drawings for information on dimensions, materials, platings and markings.

#### 2.3 SAFETY AGENCY APPROVALS

UL File Number: E29179

CSA File Number: 152514 (LR19980)

#### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

AS-73642-9998	Application Specification HDM Compliant Backplane Connectors
AS-73656-1998	Application Specification HDM Compliant BP Power Modules
AS-73670-9996	Application Specification HDM Compliant Terminal Performance
AS-73670-9997	Application Specification HDM Backplane and Daughtercard Trace
	Routing Guidelines
AS-73670-9998	Application Specification HDM Compliant and Solder Tail Daughtercard
	Connectors

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Refer to the appropriate sales drawings and other sections of this specification for additional referenced documents and specifications.

#### 4.0 RATINGS

4.1 CURRENT

Signal Contact: 1 Amp

Power: 15 Amps per blade at 30°C rise from ambient temperature

4.2 VOLTAGE

Signal Contact: 250VAC Power Contact: 500VAC

#### 4.3 CONTACT BULK RESISTANCE

Mated Signal:

A Row	13 milliohms
B Row 18 milliohm	
C Row	20 milliohms
D Row	25 milliohms
E Row	30 milliohms
F Row	32 milliohms

Power Blade: 3 milliohms maximum

#### 4.4 TEMPERATURE RANGE

Operating: -55°C to 105°C Non-operating: -55°C to 85°C

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#### 4.5 CONTACT WIPE LENGTH

5.0mm Backplane Pin	1.75mm
5.5mm Backplane Pin	2.25mm
6.0mm Backplane Pin	2.75mm
Short Power Blade	3.75mm
Medium Power Blade	4.75mm
Long Power Blade	5.75mm

#### 5.0 PERFORMANCE

#### **5.1 ELECTRICAL PERFORMANCE**

ITEM	TEST CONDITION	REQUIREMENT
CONTACT RESISTANCE (LOW LEVEL)	Mated, 100mA max, 20mV per EIA-364-TP-23	10 milliohm maximum change
INSULATION RESISTANCE	Unmated, 500VDC per EIA-364-TP-21	Initial: 5000 megohms minimum Final: 1000 megohms minimum
DIELECTRIC WITHSTANDING VOLTAGE	Unmated, 1500VAC for signal, 2000VAC for power, per EIA-364-TP-20	No breakdown or flashover
SIGNAL CONTINUITY	Mated per EIA-364-TP-87	No interrupts greater than 10 nanoseconds
COMPLIANT PIN INTERFACE RESISTANCE	Contact inserted into PCB per EIA-364-TP-23	1 milliohm maximum

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G	DATE: 2009/06/22	INTER	4 01 7		
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EII ENAME: DS72670C D					MAE: DS72670C DOC



#### **5.2 MECHANICAL PERFORMANCE**

ITEM	TEST CONDITION	REQUIREMENT
MATING FORCE	Mate daughtercard and backplane assembly per EIA-364-TP-13	0.6N per signal pin 1.3N per power blade (nominal values)
DURABILITY	250 Cycles, mated and unmated per EIA-364-TP-09	10 milliohm max change in LLCR
VIBRATION	Mated, 10-100Hz, 10g's, 24 hr, 3 axis per EIA-364-TP-28	10 milliohm max change in LLCR
MECHANICAL SHOCK	Mated, 30g half-sine, 11ms, 3 axis per EIA-364-TP-27	10 milliohm max change in LLCR
NORMAL FORCE/ SPRING RATE	Apply perpendicular force to terminal at rate of 25+/-6mm per minute	Signal: 0.5N (50 g) min Spring Rate: 12.5 g/mil deflection (nominal) Power: 1.0N (100 g) min
GUIDE PIN STRENGTH	Apply perpendicular force to guide pin tip at rate of 12.7+/-6mm per minute. Record force at 1mm pin displacement	Guide pin in plastic housing: 75N Stand alone guide pin: 130 N (nominal values)
TORQUE SETTING FOR MOUNTING SCREW	Using torque driver, turn screw into plastic guide module until screw strips out	2.5 in-lbs minimum for 1.6- 4.8mm PCB thickness

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	EC No: UCP2009-2455	DENS	SITY METRIC (HDN	Л)	<b>5</b> of <b>7</b>
G	DATE: 2009/06/22		CONNECT SYSTE	,	<b>3</b> 01 7
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				FILENA	MF: PS73670C DOC



#### **5.3 ENVIRONMENTAL PERFORMANCE**

ITEM	TEST CONDITION	REQUIREMENT
THERMAL SHOCK	Mated, 5 cycles from -55°C to 85°C per EIA-364-TP-32	10 milliohm max change in LLCR
TEMPERATURE LIFE	Mated, +105°C for 1000 hours per EIA-364-TP-17	10 milliohm max change in LLCR
HUMIDITY	Mated, 600 hours from +25°C to +65°C per EIA-364-TP-31	10 milliohm max change in LLCR
DUST	Unmated per EIA-364-TP-50	10 milliohm max change in LLCR
MIXED FLOWING GAS	10 days unmated, 10 days mated, per EIA-364-TP-65 and ASTM B827	10 milliohm max change in LLCR

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G	EC No: UCP2009-2455	DENSITY METRIC (HDM)			<b>6</b> of <b>7</b>
G	DATE: 2009/06/22	INTERCONNECT SÝSTEM			
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:	
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#### 6.0 TEST SEQUENCE

### **Bellcore Test Plan**

GROUP 1	GROUP 2	GROUP 3	GROUP 4	GROUP 5
Visual Exam	Visual Exam	Visual Exam	Visual Exam	Visual Exam
Separation Force Mate/Unmate Forces	Mate/Unmate Forces	Separation Force Mate/Unmate Forces	LLCR/CPIR	Normal Force
LLCR/CPIR	LLCR/CPIR	LLCR/CPIR	Durability (100 cycles)	Plating Thickness
Durability (100 cycles)	Thermal Shock	Temperature Life	Mate/Unmate Forces	Porosity
Separation Force	Humidity	LLCR/CPIR	LLCR	
LLCR	LLCR/CPIR	Separation Force Mate/Unmate Forces	MFG (10 days Unmated)	
Dust	Mate/Unmate Forces	Visual Exam	LLCR (After 5 & 10 days)	
LLCR	Visual Exam	Normal Force	MFG (10 days Mated)	
Vibration (3 axis)	Normal Force		LLCR (After 5 & 10 days)	
LLCR		•	Disturbance	
Mechanical Shock (3 axis)			LLCR	
LLCR/CPIR			Durability (100 cycles)	
Separation Force Mate/Unmate Forces			LLCR/CPIR	
Visual Exam			Visual Exam	
Normal Force			Normal Force	

LLCR = Low Level Contact Resistance CPIR = Compliant Pin Interface Resistance

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